

CHEMICAL MECHANICAL POLISHING ENDPOINT DETECTION SYSTEM AND

METHOD

ABSTRACT

5 The system includes a polishing pad, a pad height sensor; a window; and a
window raising mechanism. The polishing pad has an aperture with the window
vertically moveable therein. The pad height sensor is positioned above the polishing pad
and measures the vertical position of the pad before polishing. The window raising
mechanism adjusts the vertical position of the window based on information from the pad
10 height sensor. An endpoint measurement sensor can be disposed beneath the window for
in-situ measurement of the polishing process.